

Report NO.: MG00001000187

**1. Product information**

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJU30P10
Package Type :	TO-252-2L

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total	
Wafer	Silicon	7440-21-3	100.00%	0.362%	
Lead Frame	Iron	7439-89-6	0.06%		
	Phosphorus	7723-14-0	0.04%		
	Copper	7440-50-8	99.90%		
	Silver	7440-22-4	0.01%		
Wire1	Al	7429-90-5	99.99%	0.0292%	
	others	/	0.01%		
	Cr	7440-47-3			
Wire2	copper	7440-50-8	99.99%	0.1099%	
	others	/	0.01%		
Epoxy	Lead	7439-92-1	92.50%	0.8378%	
	Tin	7440-31-5	5.00%		
	Silver	7440-22-4	2.50%		
Mold Compound	Epoxy resin A	Trade Secret	5.914%	79.5755%	
	Epoxy resin B	29690-82-2	3.87%		
	Phenol Resin	Trade Secret	2.198%		
	Silica(Amorphous) A	60676-86-0	80.508%		
	Silica(Amorphous) B	7631-86-9	6.88%		
	Carbon black	1333-86-4	0.63%		
Plating	Tin	7440-31-5	100.00%	0.4773%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.